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APPLICATION NO.	FII	JING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/635,506	08/07/2003		Toshikazu Mizukoshi	OKI 361	8477
23995	7590	10/18/2004		EXAMINER	
RABIN &	•		CHEN, JACK S J		
SUITE 500	1101 14TH STREET, NW SUITE 500				PAPER NUMBER
WASHING	WASHINGTON, DC 20005				

DATE MAILED: 10/18/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

		H	ha
	Application No.	Applicant(s)	
	10/635,506	MIZUKOSHI, TOSHIKAZU	
Office Action Summary	Examiner	Art Unit	
	Jack Chen	2813	
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the	correspondence address	
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply if NO period for reply is specified above, the maximum statutory period we Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	66(a). In no event, however, may a reply be ti within the statutory minimum of thirty (30) da ill apply and will expire SIX (6) MONTHS fron cause the application to become ABANDONI	mely filed  ys will be considered timely.  n the mailing date of this communication.  ED (35 U.S.C. § 133).	
Status		<b>;</b>	
1) Responsive to communication(s) filed on 30 Ju	ily 2004.	•	
<u> </u>	action is non-final.		
3) Since this application is in condition for allowar	nce except for formal matters, pr	osecution as to the merits is	
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.	
Disposition of Claims			
4) Claim(s) 1 and 4-10 is/are pending in the application	cation.		
4a) Of the above claim(s) is/are withdraw	vn from consideration.		
5) Claim(s) is/are allowed.	,		
6)⊠ Claim(s) <u>1 and 4-10</u> is/are rejected.			
7) Claim(s) is/are objected to.			
8) Claim(s) are subject to restriction and/or	r election requirement.		
Application Papers			
9) The specification is objected to by the Examine	r.		
10)☐ The drawing(s) filed on is/are: a)☐ acce			
Applicant may not request that any objection to the			
Replacement drawing sheet(s) including the correct			
11)☐ The oath or declaration is objected to by the Ex	aminer. Note the attached Offic	e Action or form PTO-152.	
Priority under 35 U.S.C. § 119			
<ul> <li>12) Acknowledgment is made of a claim for foreign</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents</li> <li>2. Certified copies of the priority documents</li> <li>3. Copies of the certified copies of the priority</li> </ul>	s have been received. s have been received in Applica	tion No	
application from the International Bureau	-	· ·	
* See the attached detailed Office action for a list		ed.	
Attachment(s)			
1) Notice of References Cited (PTO-892)	4) Interview Summar		
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	Paper No(s)/Mail [ 5) Notice of Informal	Date Patent Application (PTO-152)	
2) Information Disclosure Statement(s) (PTO-1449 of PTO/SB/08)  Paper No(s)/Mail Date 7/13/04; 6/30/04, 4/9/ of.	6) Other:		

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## **DETAILED ACTION**

In response to the communication filed on July 30, 2004, claims 1 and 4-10 are active in this application.

## Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1, 4-6 and 10 are rejected under 35 U.S.C. 102(b) as being anticipated by Ishitsuka et al., U.S./6,242,323 B1.

Ishitsuka et al. teaches a method for forming a semiconductor device, which comprises a mask forming step comprised of sequentially forming a first insulating film 2 and a second insulating film 3 on a semiconductor substrate 1 (fig. 51, also see examples 1-3), followed by forming a mask 43 (fig. 2C) for forming trenches on the second insulating film by patterning so as to expose a surface area of the second insulating film corresponding to each trench formed on the semiconductor substrate (fig. 2D); a trench forming step comprised of etching a portion extending from the surface area of the exposed second insulating film to an in-depth part of the semiconductor substrate using the mask for forming trenches 4a (fig. 51), thereby forming the trenches on the semiconductor substrate; a depositing step comprised of removing the mask for forming trenches (figs. 2E-2F), followed by depositing a third insulating film 4a by filling a third insulating film into each trench up to the height to cover the second insulating film (fig. 53); a second oxide film 5 forming step performed through the third insulating film and after said

depositing a third insulating film, and being comprised of subjecting the semiconductor substrate at a cornered portion of each trench to thermal oxidation, thereby forming a second oxide film (fig. 54); a planarizing step performed after said second oxide film forming step, and comprising polishing and planarizing the third insulating film so as to expose the second insulating film (fig. 2H); and an element isolation portion forming step comprised of removing the second insulating film and the first insulating film, followed by etching the third insulating film such that a part of the third insulating film remains inside each trench, thereby forming element isolating portion 36 (fig. 2I, also see examples 1-3 for more details), see figs. 1A-70; cols. 1-40 for more details.

Re claim 4, wherein the first insulating film is silicon oxide 32 (fig. 2C) and the second insulating film is a silicon nitride film 42 (fig. 2C).

Re claims 5-6, wherein the third insulating film is a silicon oxide film 36 (fig. 2G).

Re claim 10, wherein said second oxide film forming step includes supplying oxygen from an upper side of the third insulating film so that the oxygen is diffused into the third insulating film, and so that an oxidative reaction starts at the cornered portion (i.e., see col. 2, lines 1-15).

## Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

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Claims 7-9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ishitsuka et al., U.S./6,242,323 B1 in view of Watanabe, U.S./6,417,073 B2.

Ishitsuka et al. disclosed above, however, Ishitsuka et al. is silent to using HDP-CVD method for forming silicon oxide.

Watanabe teaches a method for filling the trench with silicon oxide 311 (fig. 7A; col. 1, lines 40-45) by using HDP-CVD method.

Therefore, the subject matter as a whole would have been obvious to one having ordinary skill in the art at the time the invention was made to use HDP-CVD silicon oxide as taught by Watanabe in the method of Ishitsuka et al. in order to provide good isolation, excellent uniformity, conformal step coverage, large wafer capacity and high throughput.

## Response to Arguments

Applicant's arguments with respect to claims 1 and 4-10 have been considered but are most in view of the new ground(s) of rejection.

#### Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, THIS ACTION IS MADE FINAL. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO

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MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jack Chen whose telephone number is (571)272-1689. The examiner can normally be reached on Monday-Friday (9:00am-6:30pm) alternate Monday off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl W Whitehead can be reached on (571)272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Jack Chen

Primary Examiner

Art Unit 2813

- Tweek